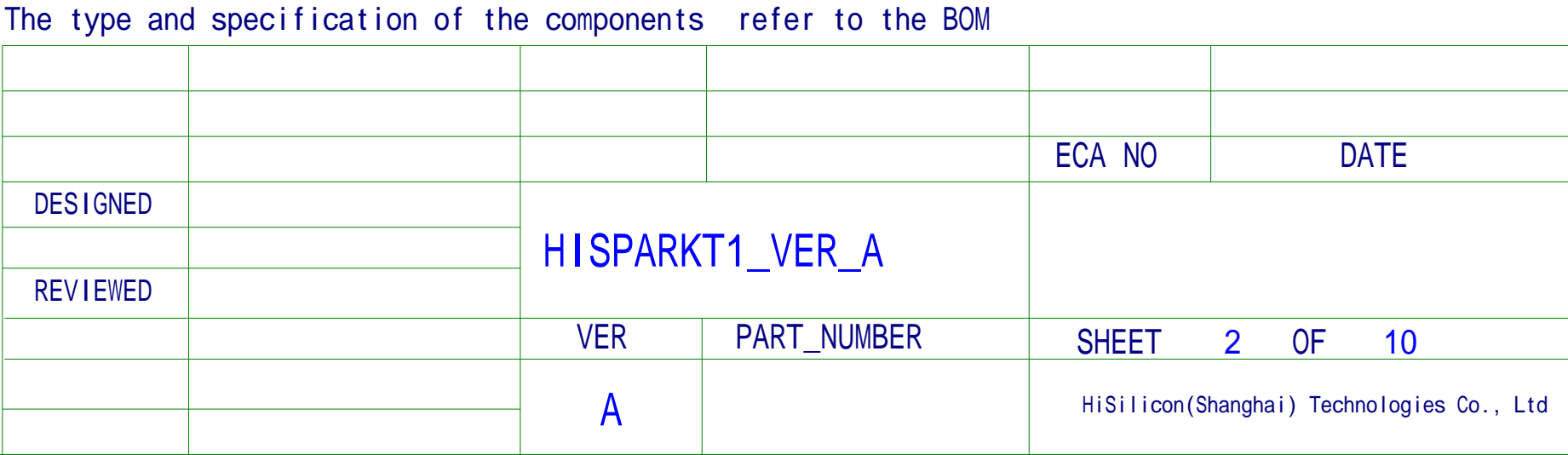
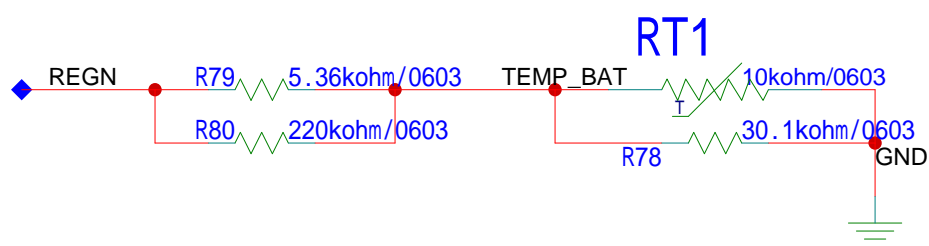


The type and specification of the components refer to the BOM

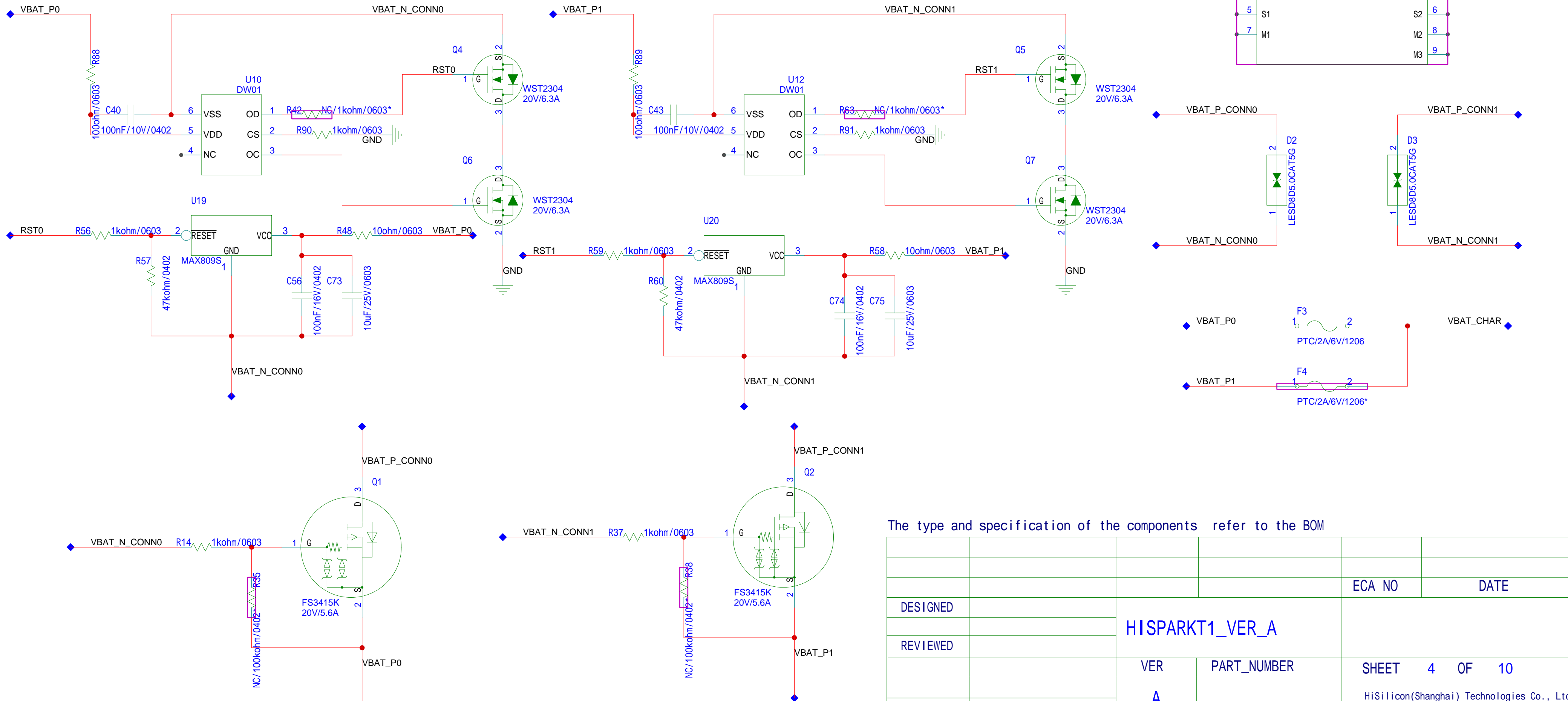
				ECA NO	DATE
DESIGNED		HISPAKT1_VER_A			
REVIEWED					
		VER	PART_NUMBER	SHEET 1 OF 10	
		A		HiSilicon(Shanghai) Technologies Co., Ltd	

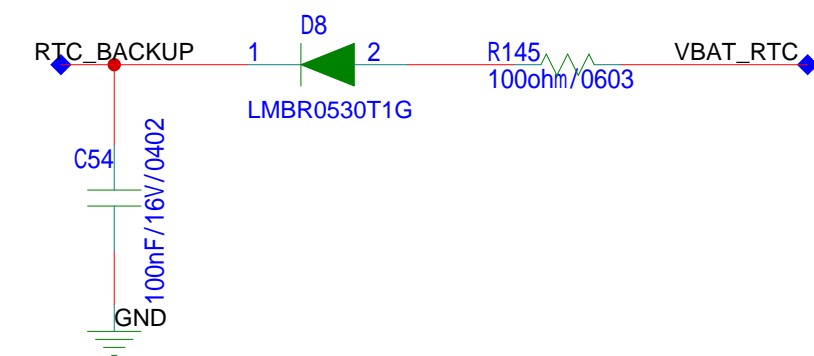
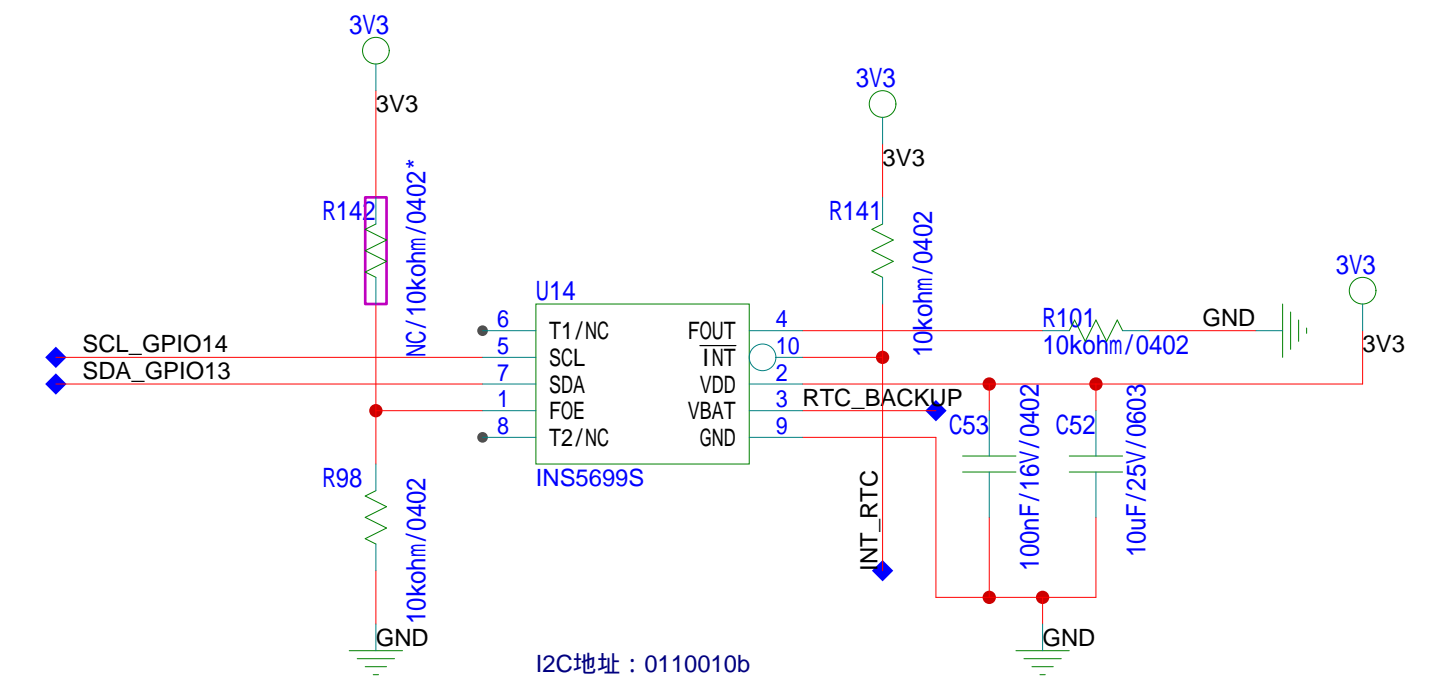
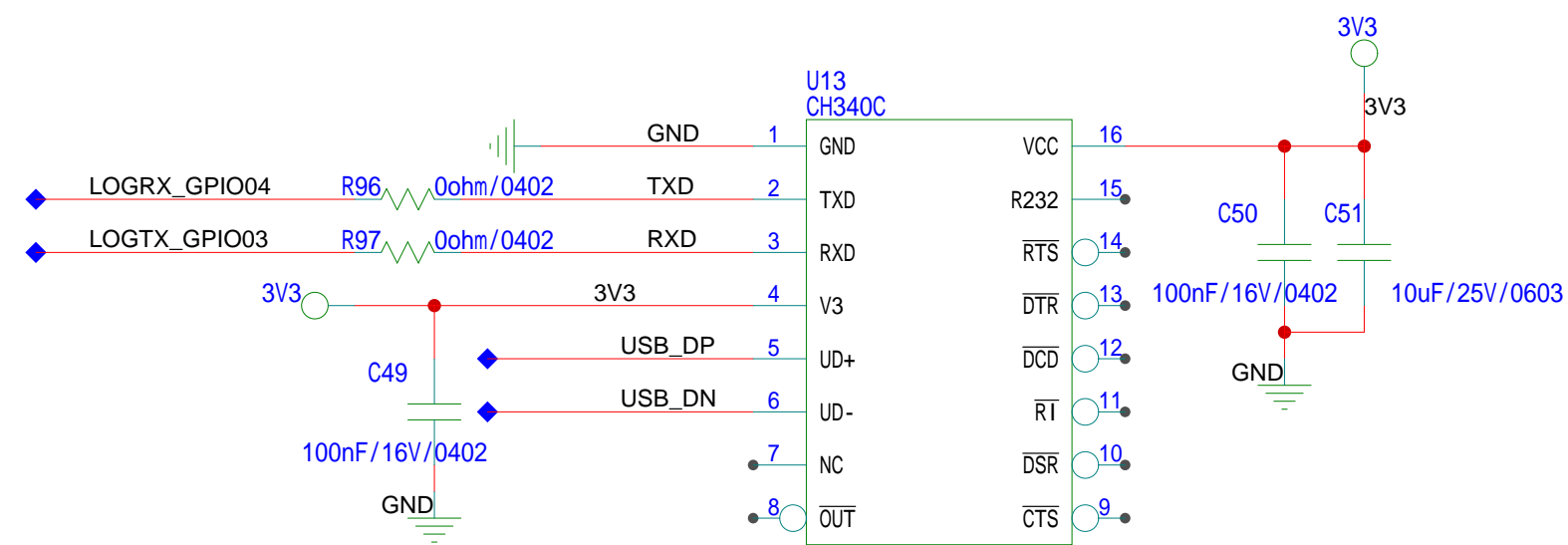
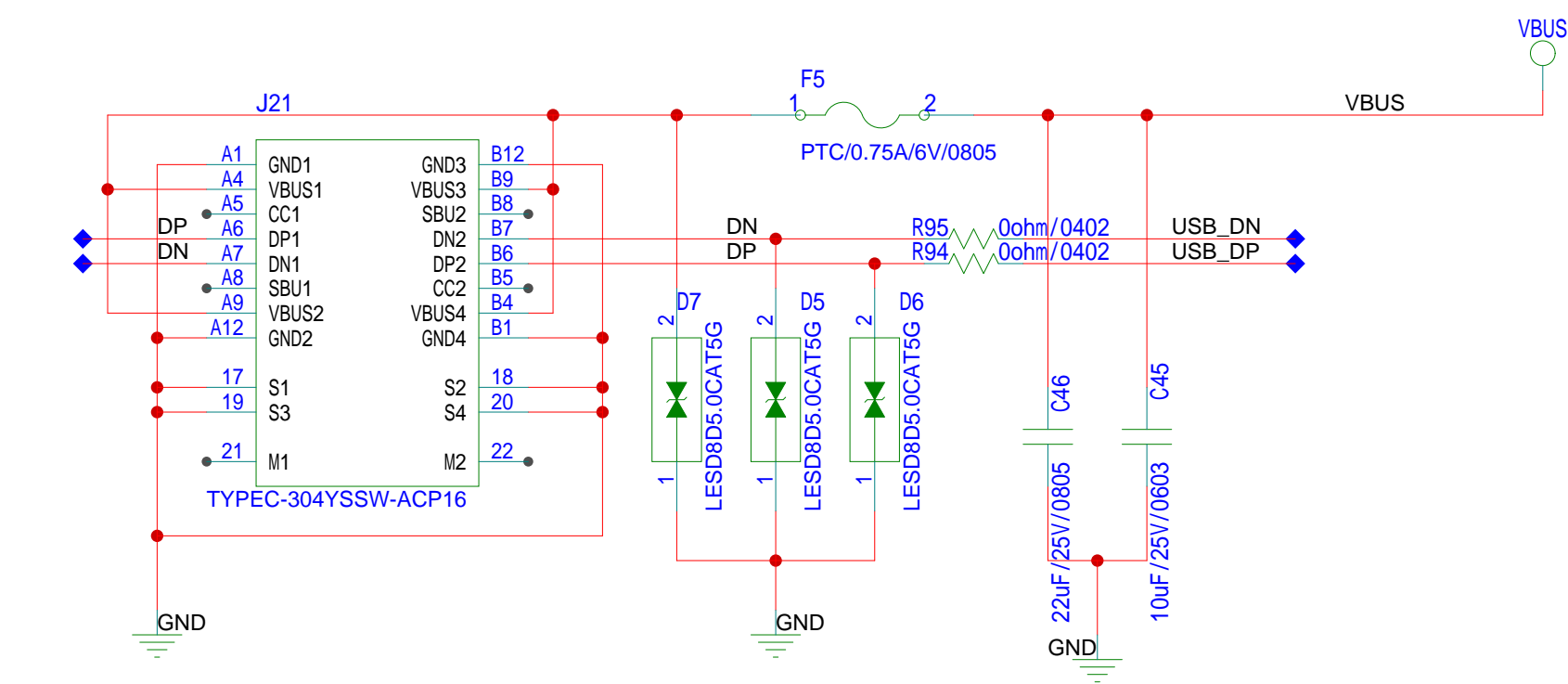






## 电池防护

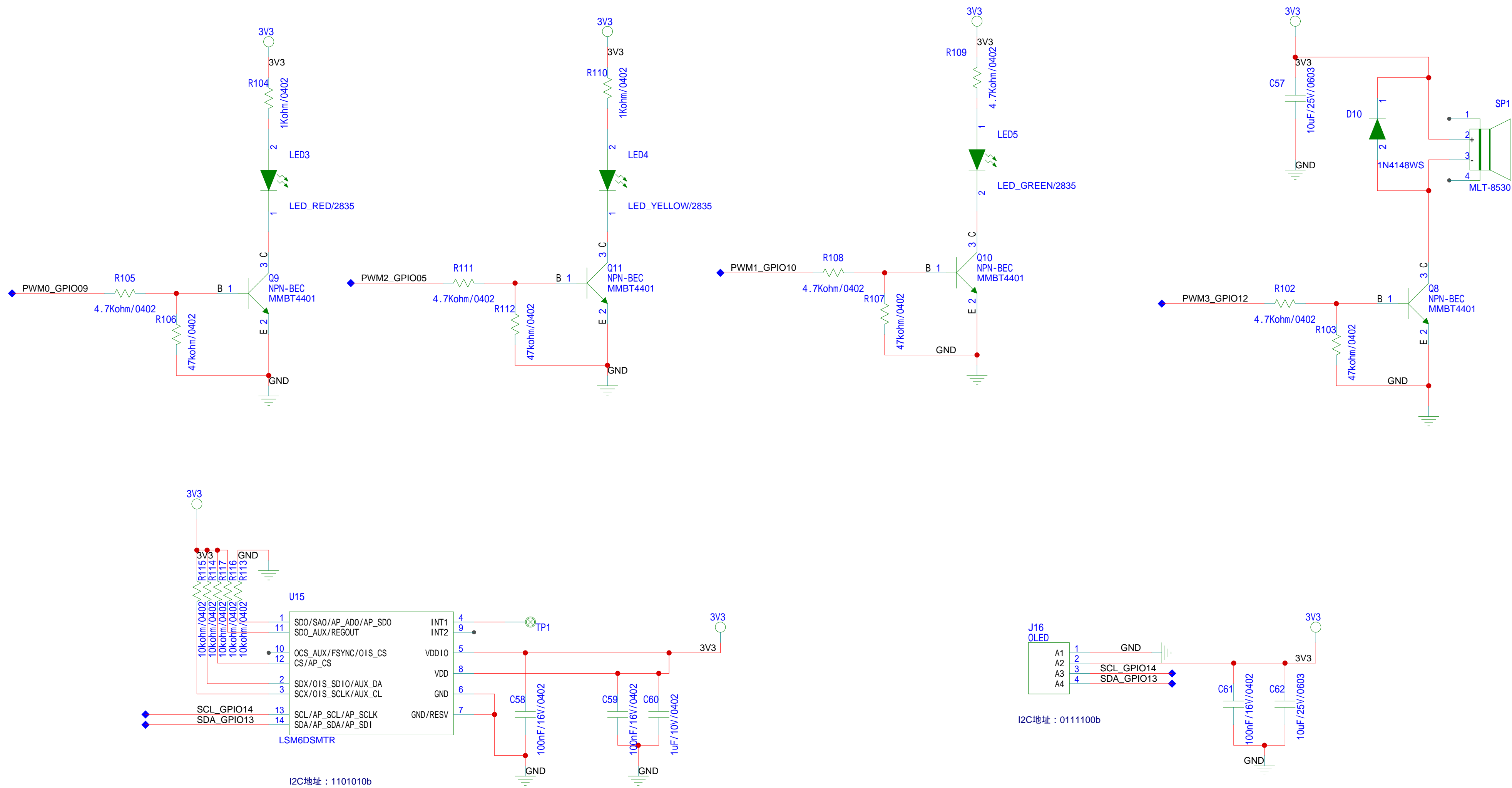




The type and specification of the components refer to the BOM

				ECA NO	DATE
DESIGNED		HISPARKT1_VER_A			
REVIEWED					
		VER	PART_NUMBER	SHEET 5 OF 10	
		A		HiSilicon(Shanghai) Technologies Co., Ltd	





The type and specification of the components refer to the BOM

				ECA NO	DATE
DESIGNED		HISPARKT1_VER_A			
REVIEWED					
		VER	PART_NUMBER	SHEET	6 OF 10
		A		HiSilicon(Shanghai) Technologies Co., Ltd	

A

B

C

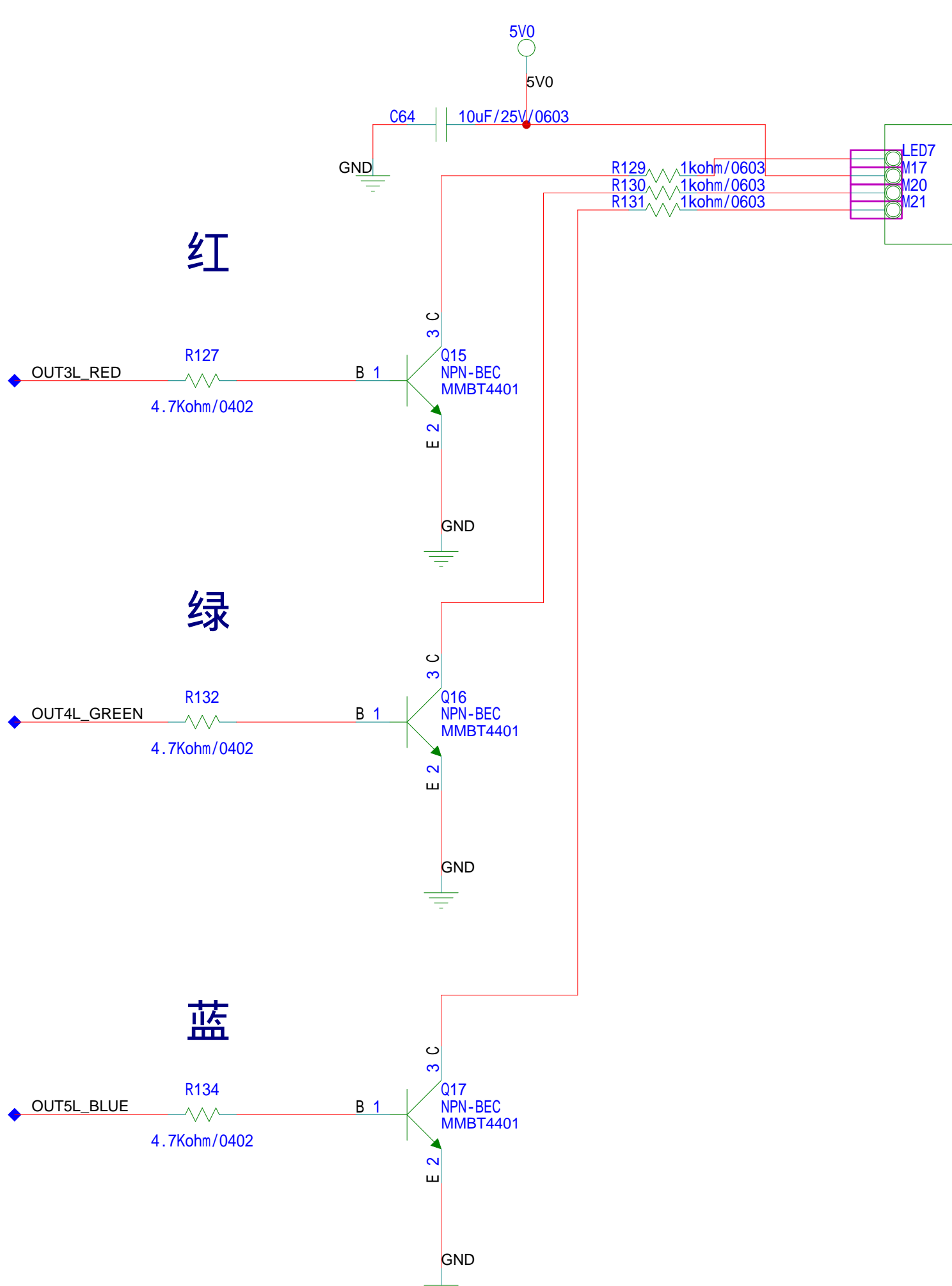
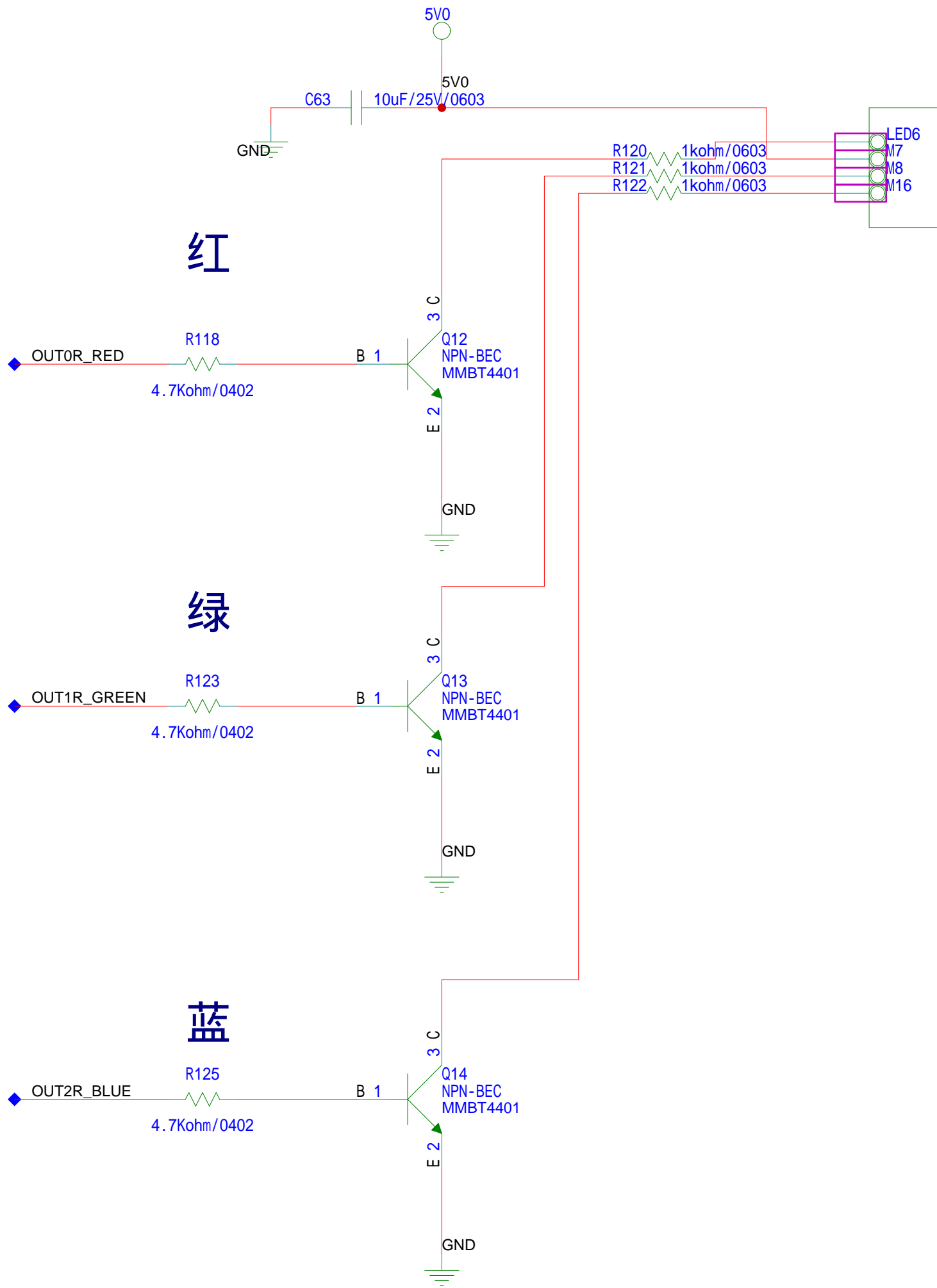
D

A

B

C

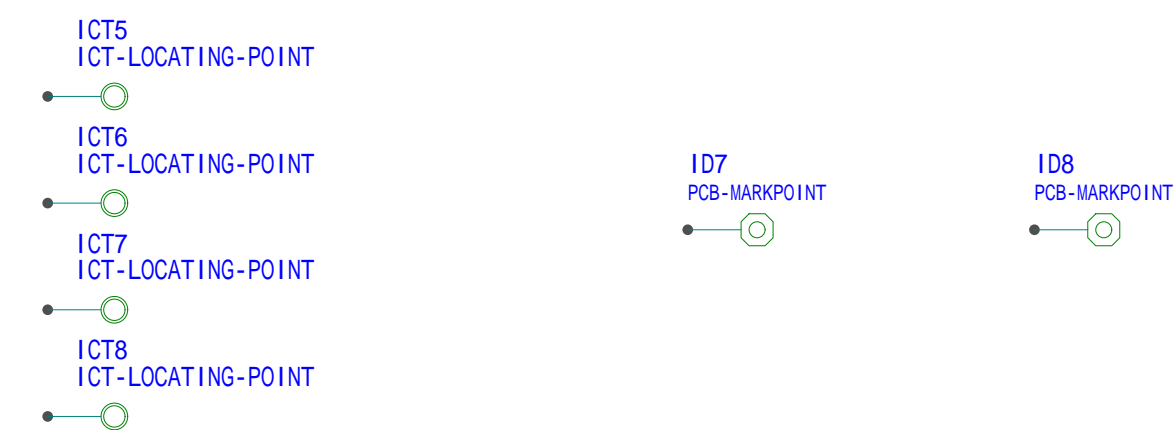
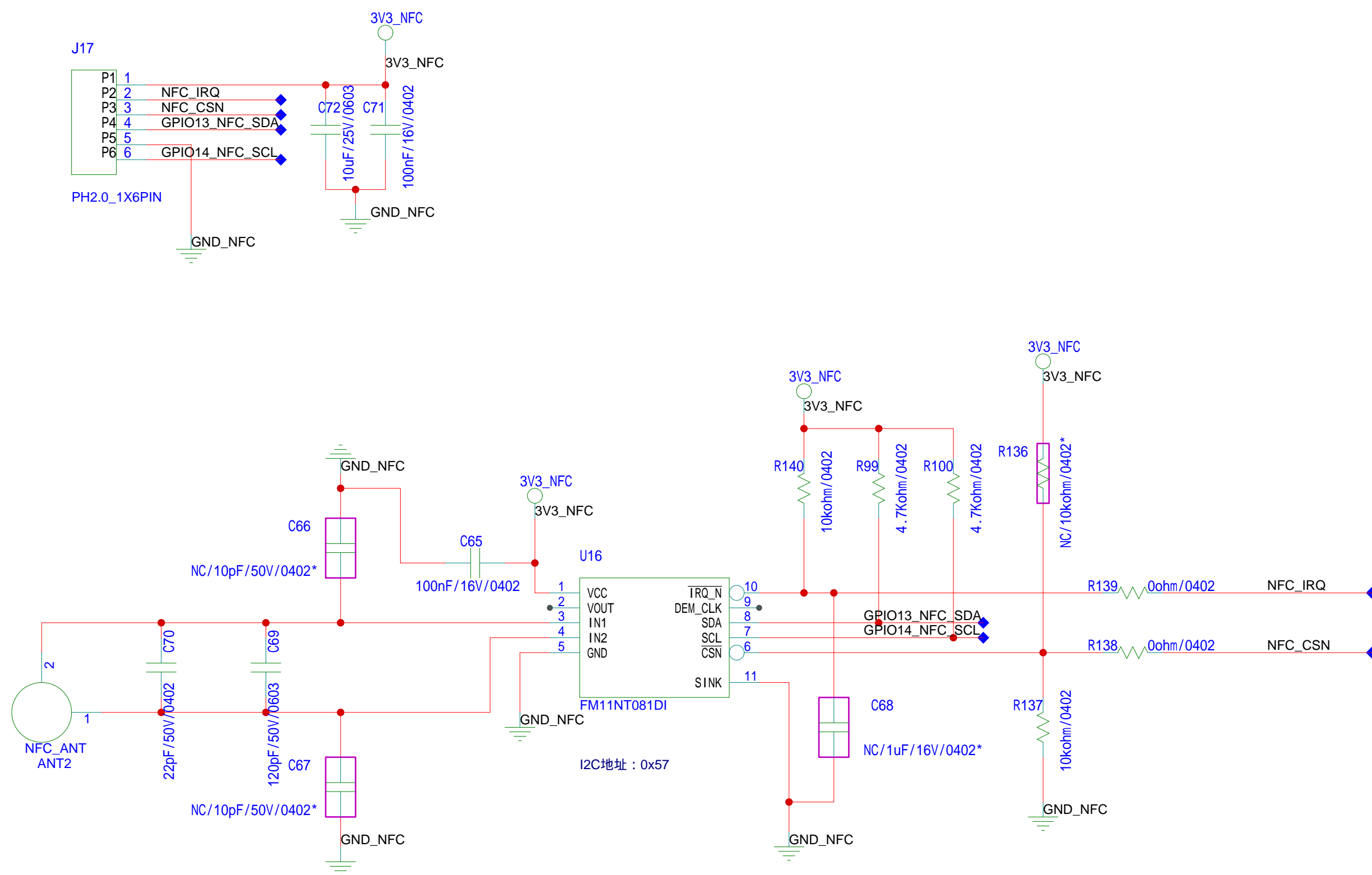
D



1 : 正极  
2 : 红色  
3 : 绿色  
4 : 蓝色

The type and specification of the components refer to the BOM

				ECA NO	DATE
DESIGNED		HISPARKT1_VER_A			
REVIEWED					
		VER	PART_NUMBER	SHEET	7 OF 10
		A		HiSilicon(Shanghai) Technologies Co., Ltd	



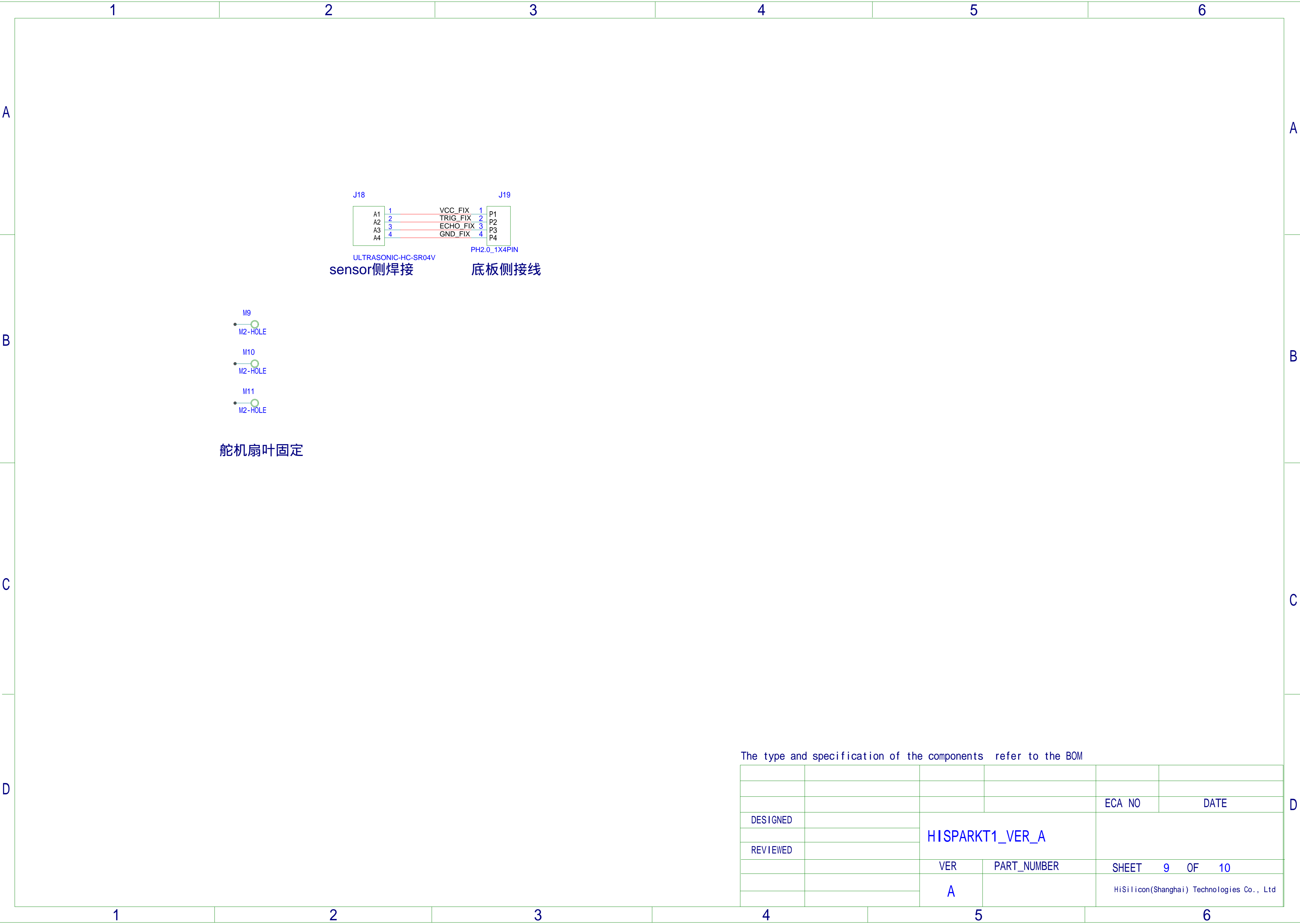
## 螺丝孔

## 光学定位

The type and specification of the components refer to the BOM

				ECA NO	DATE
DESIGNED		HISPARKT1_VER_A			
REVIEWED					
		VER	PART_NUMBER	SHEET 8 OF 10	
		A		HiSilicon(Shanghai) Technologies Co., Ltd	





A

B

C

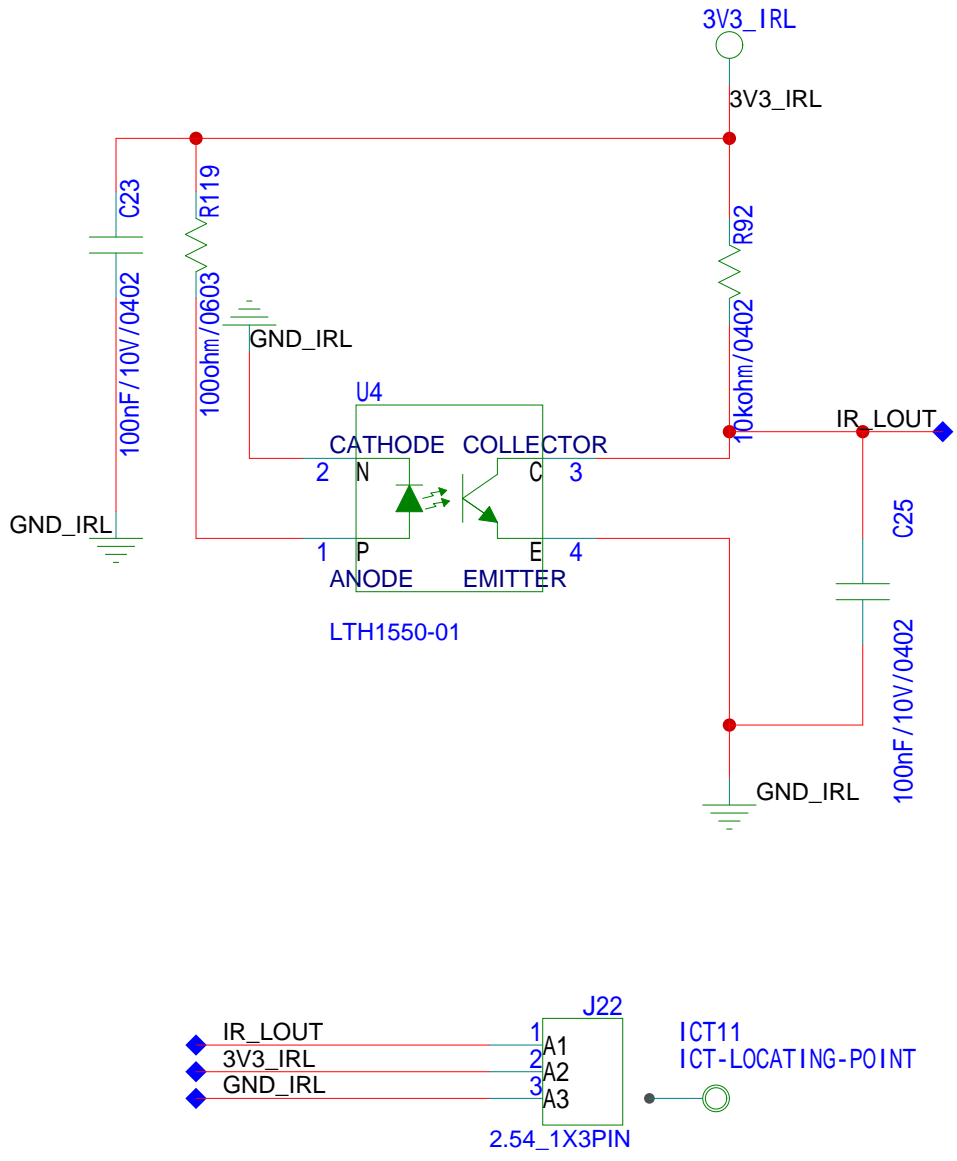
D

A

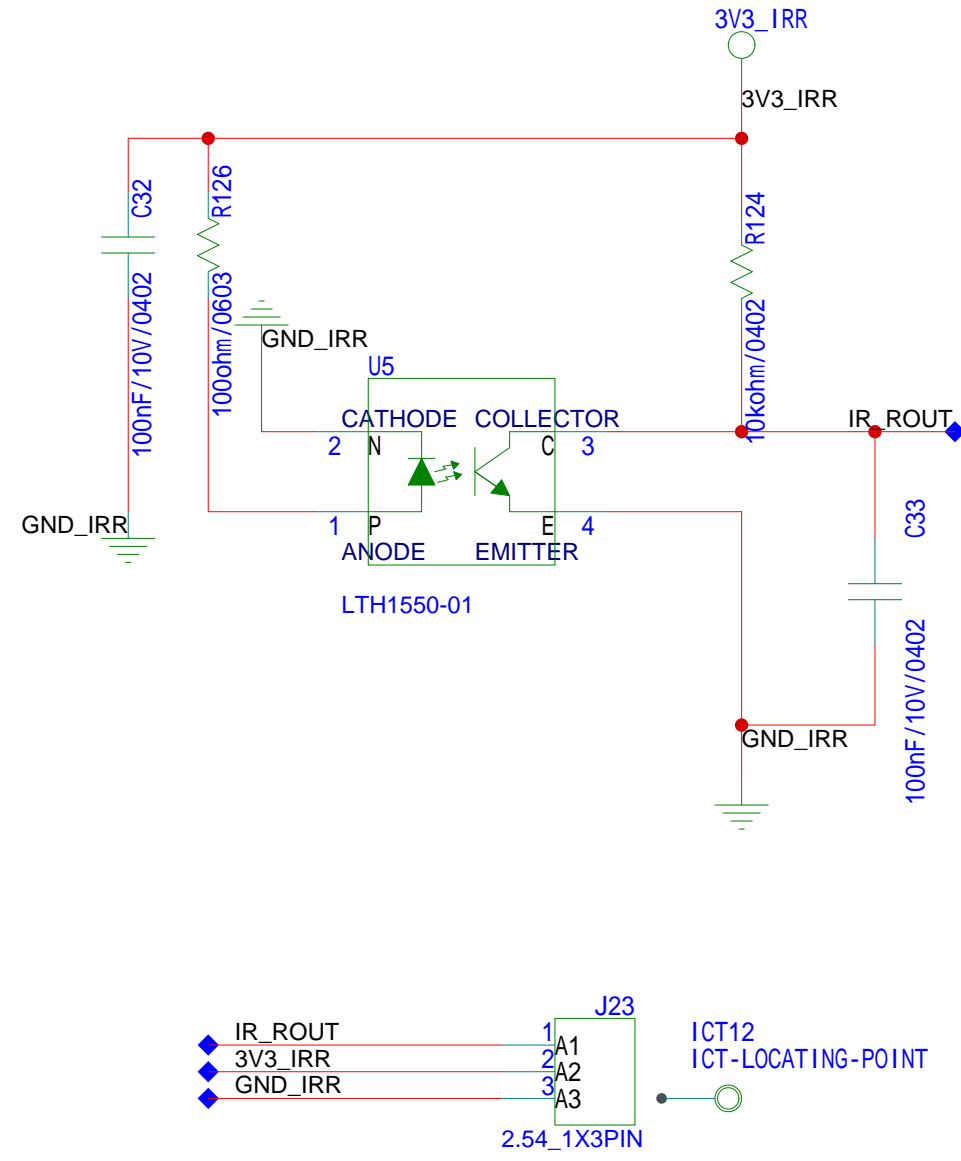
B

C

D



左红外小板



右红外小板

The type and specification of the components refer to the BOM

				ECA NO	DATE
DESIGNED		HISPARKT1_VER_A			
REVIEWED					
		VER	PART_NUMBER	SHEET	10 OF 10
		A		HiSilicon(Shanghai) Technologies Co., Ltd	